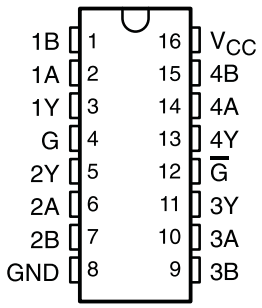
QML CLASS V RS-422 QUADRUPLE DIFFERENTIAL LINE RECEIVER

Check for Samples: AM26LS33A-SP

FEATURES

- **AM26LS33A Devices Meet or Exceed the Requirements of ANSI TIA/EIA-422-B, TIA/EIA-423-B, and ITU Recommendations V.10 and V.11**
- **±15-V Common-Mode Range With ±500-mV Sensitivity**
- **Input Hysteresis . . . 50 mV Typical**
- **Operate From a Single 5-V Supply**
- **Low-Power Schottky Circuitry**
- **3-State Outputs**
- **Complementary Output-Enable Inputs**
- **Input Impedance . . . 12 kΩ Minimum**
- **Designed to Be Interchangeable With Advanced Micro Device AM26LS33™**
- **QML-V Qualified, SMD 5962-78020**
- **Military Temperature Range (-55°C to 125°C)**
- **Rad-Tolerant: 25 kRad (Si) TID** (1)

J PACKAGE
(TOP VIEW)



(1) Radiation tolerance is a typical value based upon initial device qualification with dose rate = 10 mrad/sec. Radiation Lot Acceptance Testing is available - contact factory for details.

DESCRIPTION

The AM26LS33A is a quadruple differential line receiver for balanced and unbalanced digital data transmission. The enable function is common to all four receivers and offers a choice of active-high or active-low input. The 3-state outputs permit connection directly to a bus-organized system. Fail-safe design ensures that, if the inputs are open, the outputs always are high.

Compared to the AM26LS33, the AM26LS33A incorporates an additional stage of amplification to improve sensitivity. The input impedance has been increased, resulting in less loading of the bus line. The additional stage has increased propagation delay; however, this does not affect interchangeability in most applications.

The AM26LS33A is characterized for operation over the temperature range of –55°C to 125°C.

ORDERING INFORMATION(1)

T_A	PACKAGE(2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	CDIP - J	5962-7802007VEA	5962-7802007VEA

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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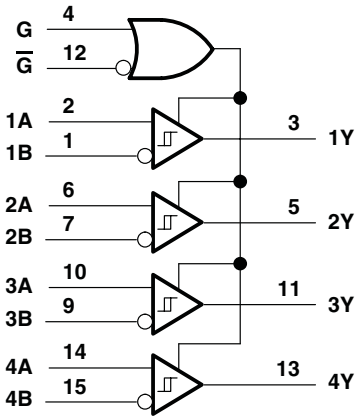
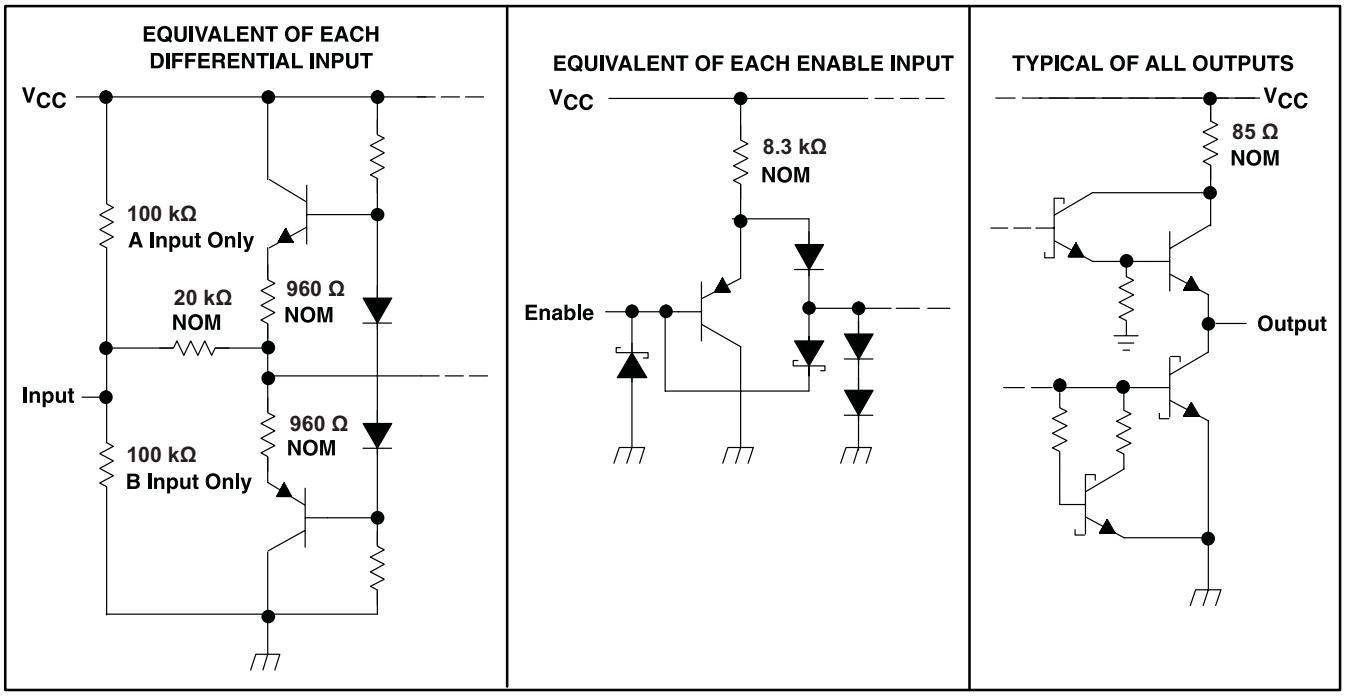
Table 1. FUNCTION TABLE
Each Receiver

DIFFERENTIAL A–B	ENABLES		OUTPUT Y
	G	$\overline{G}$	
$V_{ID} \geq V_{IT+}$	H	X	H
	X	L	H
$V_{IT-} \leq V_{ID} \leq V_{IT+}$	H	X	?
	X	L	?
$V_{ID} \leq V_{IT-}$	H	X	L
	X	L	L
X	L	H	Z
Open	H	X	H
	X	L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



SCHEMATICS OF INPUTS AND OUTPUTS



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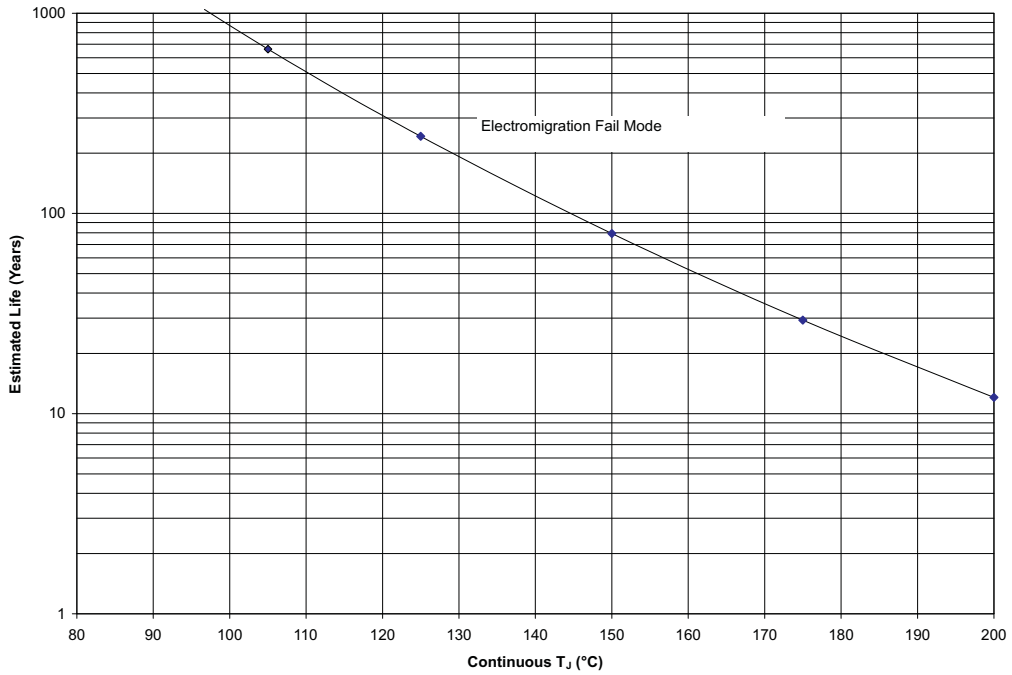
ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage(2)			7	V
V_I	Input voltage	Any differential input		±25	V
		Other inputs		7	
V_{ID}	Differential input voltage(3)			±25	V
	Continuous total power dissipation		See Dissipation Ratings Table		
	Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds			300	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to the network ground terminal.
(3) Differential voltage values are at the noninverting (A) input terminals with respect to the inverting (B) input terminals.



A. See datasheet for absolute maximum and minimum recommended operating conditions.

B. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).

Figure 1. AM26LS33A 16/J Package Operating Life Derating Chart

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RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_{IC}	Common-mode input voltage			±15	V
I_{OH}	High-level output current			–440	μA
I_{OL}	Low-level output current			8	mA
T_A	Operating free-air temperature	-55		125	°C

ELECTRICAL CHARACTERISTICS

over recommended ranges of V_{CC}, V_{IC}, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	$V_O = V_{OH}$min, I_{OH} = –440 μA -15 V ≤ VIC ≤ 15 V				0.5	V
$V_{IT–}$	Negative-going input threshold voltage	V_O = 0.45 V , I_{OL} = 8 mA -15 V ≤ VIC ≤ 15 V		–0.5(2)			V
V_{hys}	Hysteresis voltage ($V_{IT+} – V_{IT–}$)				50		mV
V_{IK}	Enable-input clamp voltage	V_{CC} = 4.5 V,	I_I = –18 mA			–1.5	V
V_{OH}	High-level output voltage	V_{CC} = 4.5 V, V_{ID} = 1 V, $V_{I(G)}$ = 0.8 V, I_{OH} = –440 μA		2.5			V
V_{OL}	Low-level output voltage	V_{CC} = 4.5 V, V_{ID} = –1 V, $V_{I(G)}$ = 0.8 V	I_{OL}= 4 mA			0.4	V
			I_{OL}= 8 mA			0.45	
I_{OZ}	Off-state (high-impedance state) output current	V_{CC} = 5.5 V	V_O = 2.4 V			20	μA
			V_O = 0.4 V			–20	
I_I	Line input current	V_I = 15 V,	Other input at –10 V to 15 V			1.2	mA
		V_I = –15 V,	Other input at –15 V to 10 V			–1.7	
$I_{I(EN)}$	Enable input current	V_I = 5.5 V, V_{CC} = 5.5 V				100	μA
I_H	High-level enable current	V_I = 2.7 V, V_{CC} = 5.5 V				20	μA
I_L	Low-level enable current	V_I = 0.4 V, V_{CC} = 5.5 V				–0.36	mA
r_i	Input resistance	V_{IC} = –15 V to 15 V,	One input to ac ground	12	15		kΩ
I_{OS}	Short-circuit output current(3)	V_{CC} = MAX, V_{ID} = 1 V, V_O = 0 V		–15		–85	mA
I_{CC}	Supply current	V_{CC} = MAX, data inputs = GND,	All outputs disabled		52	70	mA

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C, and V_{IC} = 0.
(2) The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.
(3) Not more than one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second.

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SWITCHING CHARACTERISTICS

V_{CC} = 5 V, over operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	C_L = 15 pF,	See Figure 2		20	35	ns
			T_A = –55°C to 125°C			53	
t_{PHL}	Propagation delay time, high-to-low-level output	C_L = 15 pF,	See Figure 2		22	35	ns
			T_A = –55°C to 125°C			53	
t_{PZH}	Output enable time to high level	C_L = 15 pF,	See Figure 2		17	25	ns
			T_A = –55°C to 125°C			38	
t_{PZL}	Output enable time to low level	C_L = 15 pF,	See Figure 2		20	25	ns
			T_A = –55°C to 125°C			38	
t_{PHZ}	Output disable time from high level	C_L = 15 pF,	See Figure 2		21	30	ns
			T_A = –55°C to 125°C			45	
t_{PLZ}	Output disable time from low level	C_L = 15 pF,	See Figure 2		30	40	ns
			T_A = –55°C to 125°C			60	

(1) All typical values are at V_{CC} = 5 V, T_A = 25°C, and V_{IC} = 0.

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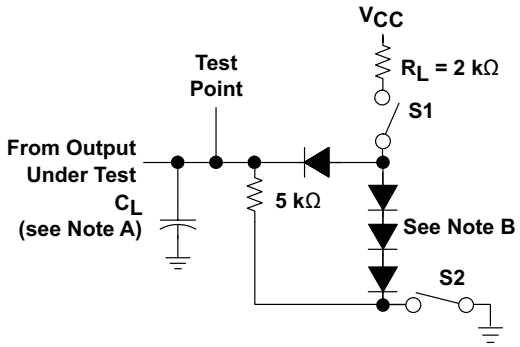
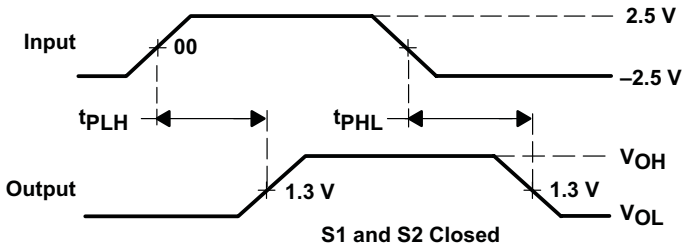
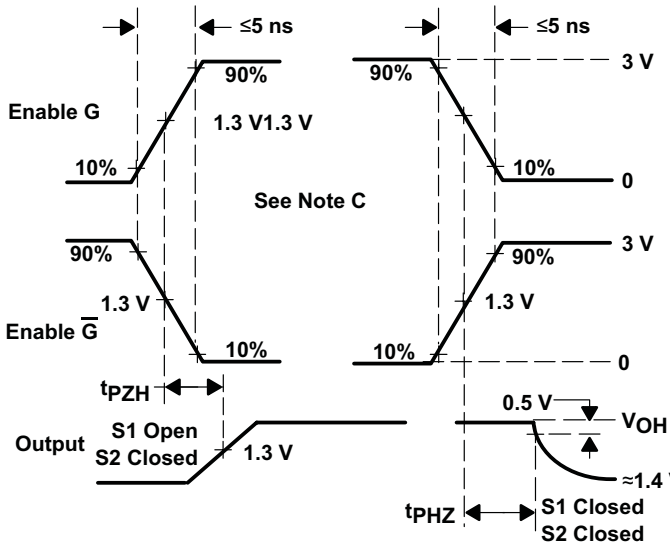
PARAMETER MEASUREMENT INFORMATION



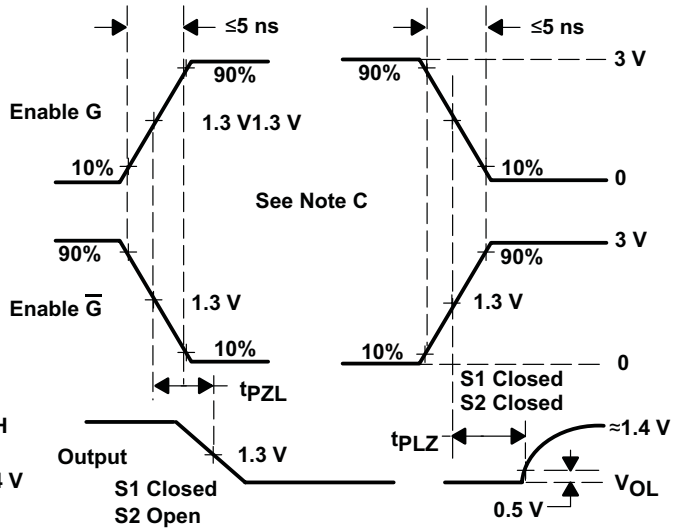
TEST CIRCUIT



VOLTAGE WAVEFORMS FOR t_{PLH}, t_{PHL}



VOLTAGE WAVEFORMS FOR t_{PHZ}, t_{PZH}



VOLTAGE WAVEFORMS FOR t_{PLZ}, t_{PZL}

NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Enable G is tested with $\overline{G}$ high; $\overline{G}$ is tested with G low.

Figure 2. Test Circuit and Voltage Waveforms

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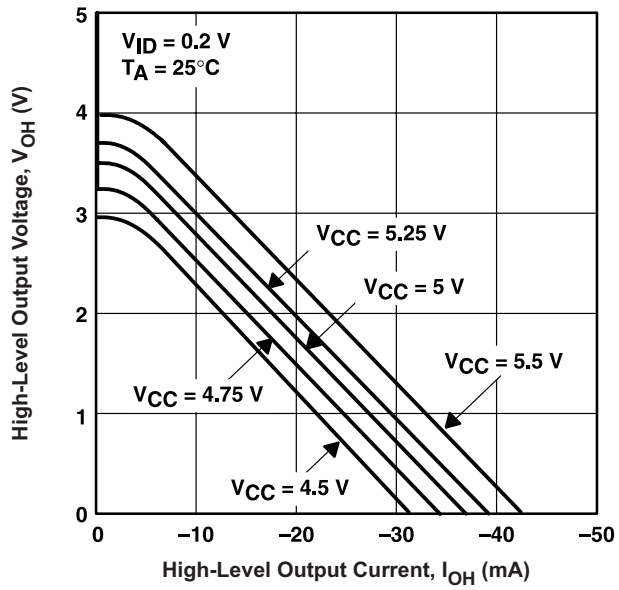
TYPICAL CHARACTERISTICS

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT



† V_{CC} = 5.5 V and V_{CC} = 4.5 V applies to M-suffix devices only.

Figure 3.

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

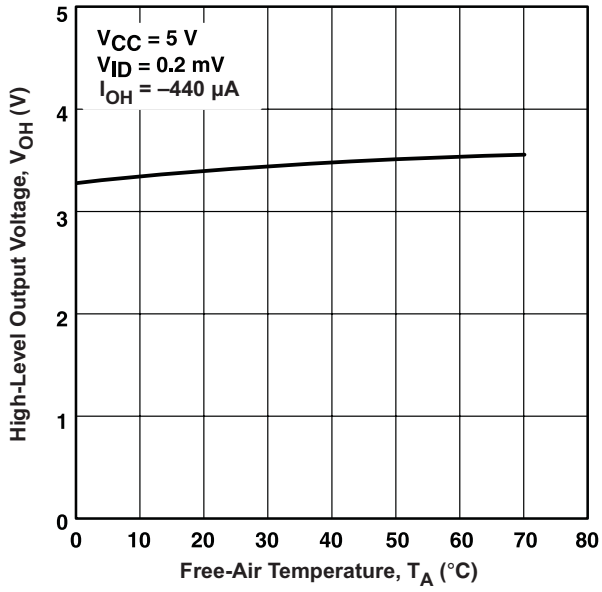


Figure 4.

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

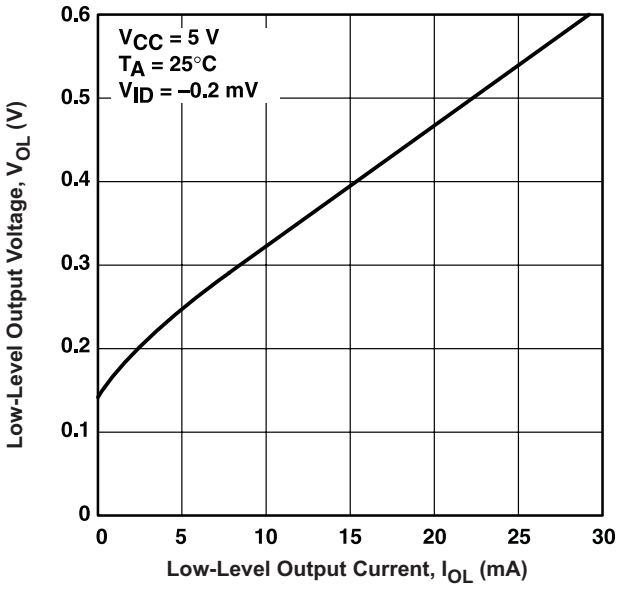


Figure 5.

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

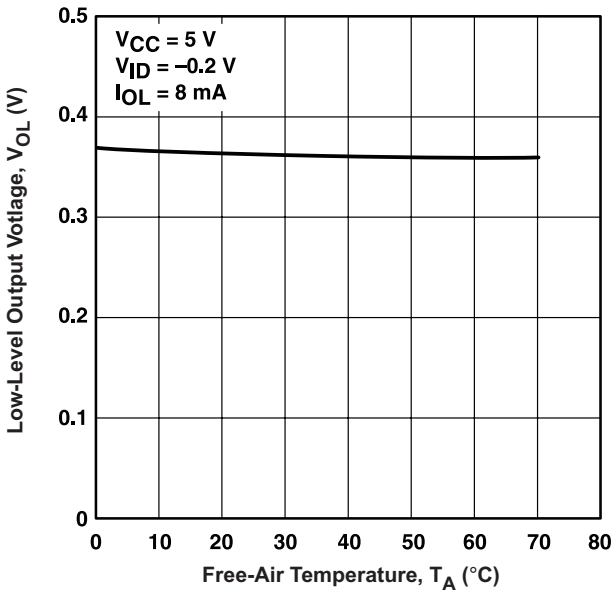


Figure 6.

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TYPICAL CHARACTERISTICS (continued)

OUTPUT VOLTAGE
vs
ENABLE G VOLTAGE

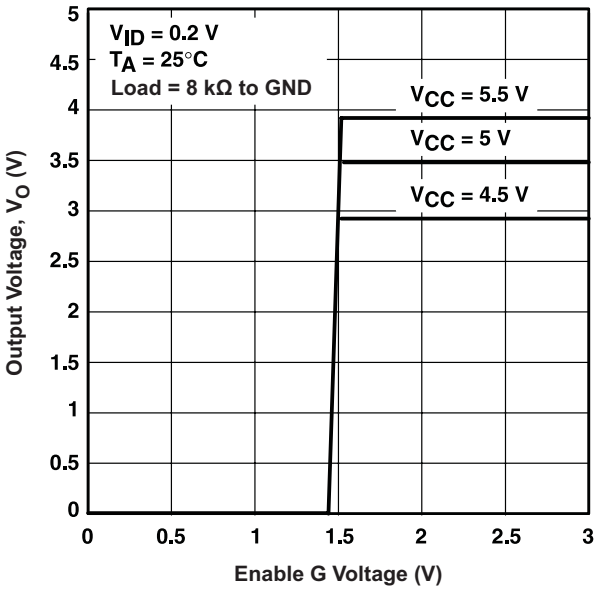

Figure 7.

OUTPUT VOLTAGE
vs
ENABLE G VOLTAGE

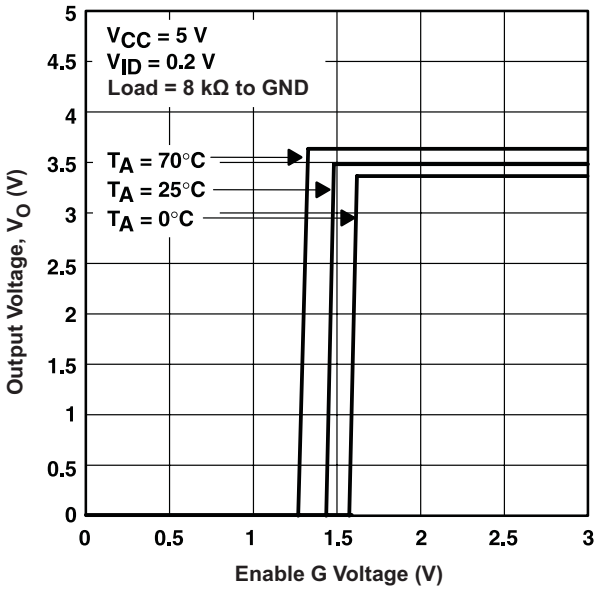

Figure 8.

OUTPUT VOLTAGE
vs
ENABLE G VOLTAGE

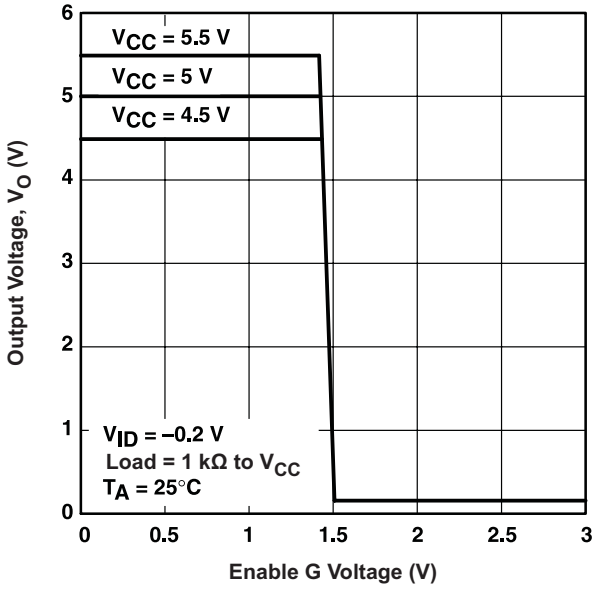

Figure 9.

OUTPUT VOLTAGE
vs
ENABLE G VOLTAGE

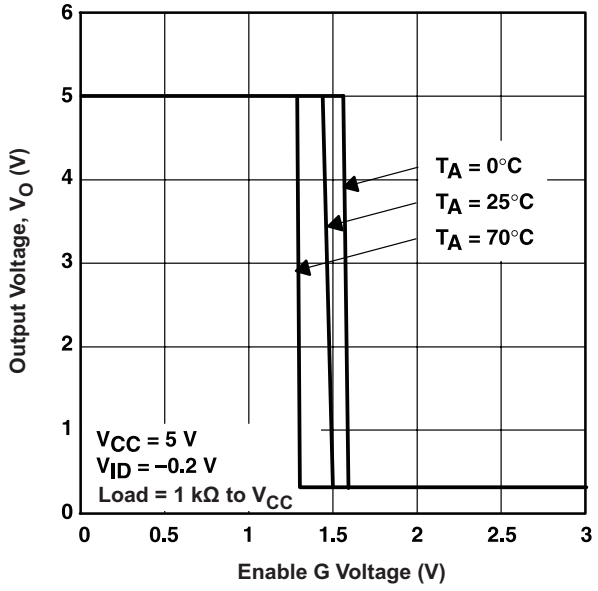

Figure 10.

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TYPICAL CHARACTERISTICS (continued)

OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

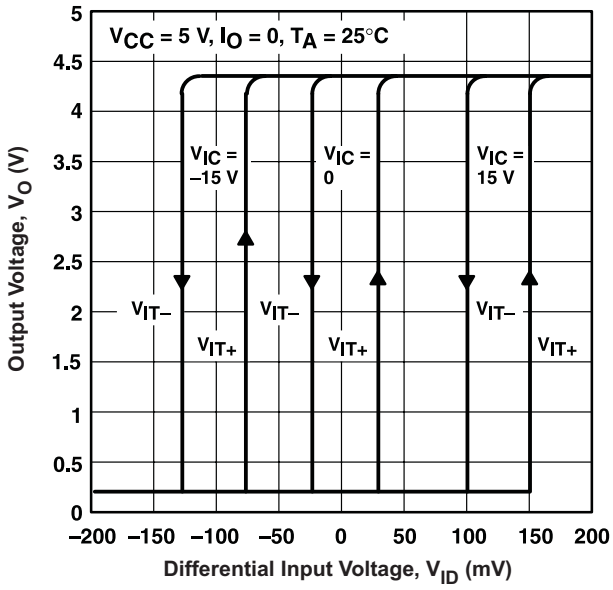
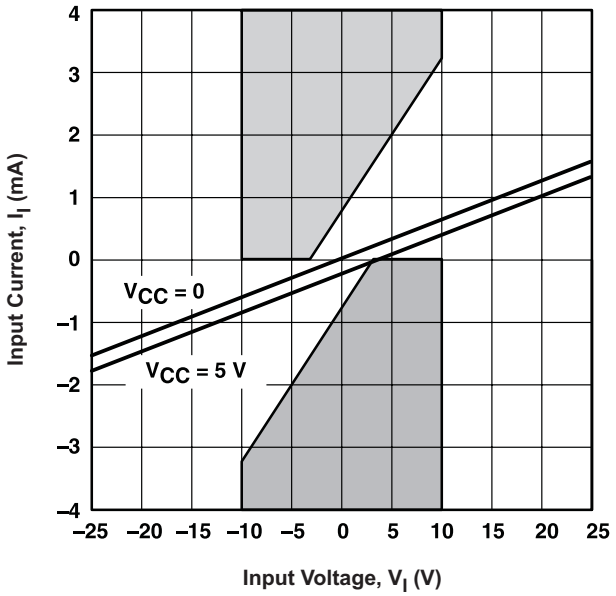


Figure 11.

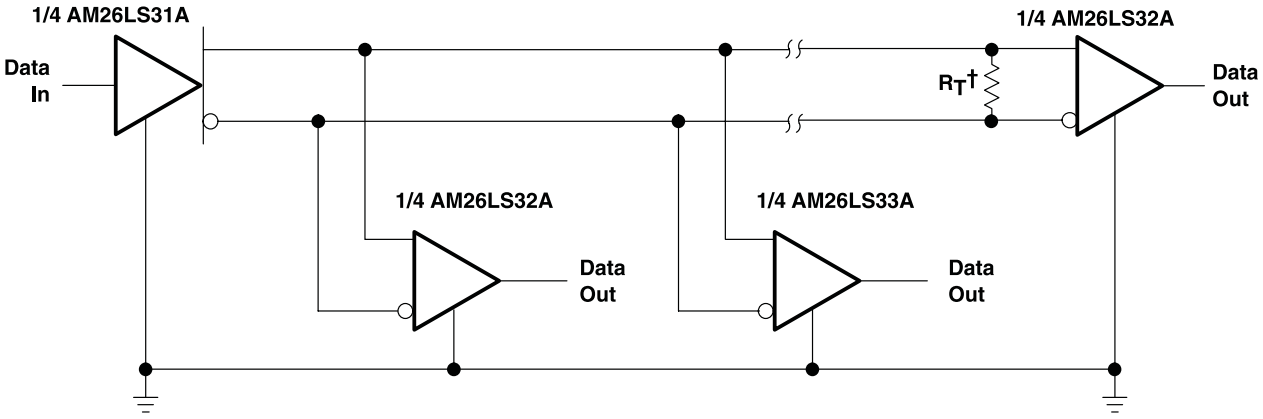
INPUT CURRENT vs INPUT VOLTAGE



The unshaded area shows requirements of paragraph 4.2.1 of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B.

Figure 12.

APPLICATION INFORMATION



† R_T equals the characteristic impedance of the line.

Figure 13. Circuit with Multiple Receivers

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-7802007VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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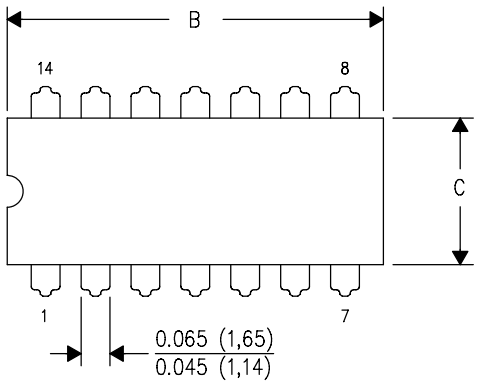
OTHER QUALIFIED VERSIONS OF AM26LS33A-SP :
- Catalog: AM26LS33A
- Military: AM26LS33AM

NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

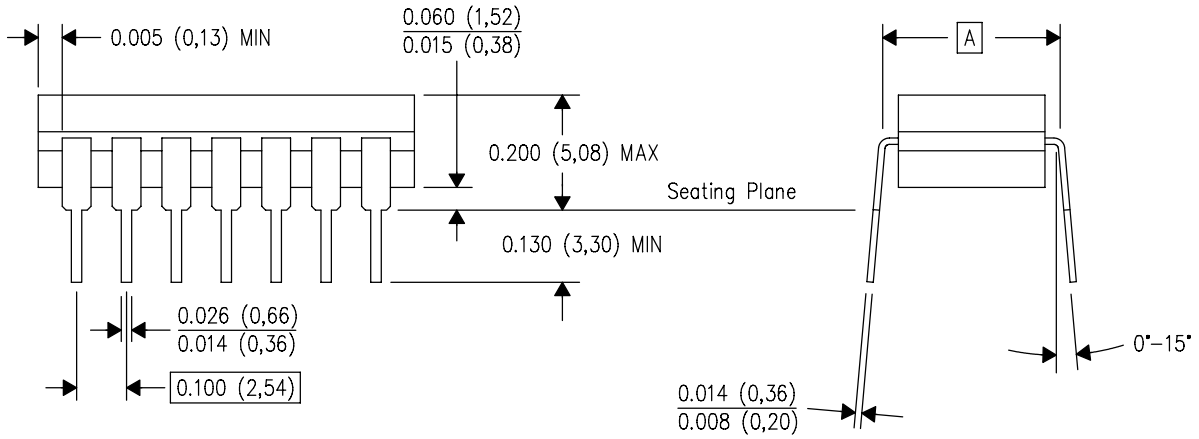
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

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